



Description

The HSBA0040 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

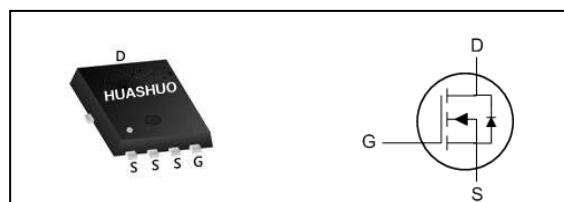
The HSBA0040 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

Product Summary

V _{DS}	100	V
R _{DS(ON),max}	14	mΩ
I _D	64	A

PRPAK5X6 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	100	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _c =25°C	Continuous Drain Current, V _{GS} @ 10V _{1,6}	64	A
I _D @T _c =100°C	Continuous Drain Current, V _{GS} @ 10V _{1,6}	40	A
I _{DM}	Pulsed Drain Current ²	130	A
EAS	Single Pulse Avalanche Energy ³	180	mJ
I _{AS}	Avalanche Current	60	A
P _D @T _c =25°C	Total Power Dissipation ⁴	89	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	62	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	1.4	°C/W



Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	100	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=10\text{A}$	---	---	14	$\text{m}\Omega$
	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=8\text{A}$	---	---	17	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=250\mu\text{A}$	1.2	---	2.4	V
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=80\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=25^\circ\text{C}$	---	---	1	uA
		$\text{V}_{\text{DS}}=80\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=55^\circ\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=5\text{V}$, $\text{I}_D=20\text{A}$	---	30	---	S
R_g	Gate Resistance	$\text{V}_{\text{DS}}=0\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	1.2	---	Ω
Q_g	Total Gate Charge (10V)	$\text{V}_{\text{DS}}=80\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=10\text{A}$	---	75	---	nC
Q_{gs}	Gate-Source Charge		---	15.5	---	
Q_{gd}	Gate-Drain Charge		---	20.3	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=40\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{R}_g=3.3\Omega$, $\text{I}_D=10\text{A}$	---	18.5	---	ns
T_r	Rise Time		---	8.8	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	58.8	---	
T_f	Fall Time		---	15.8	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=25\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	4708	---	pF
C_{oss}	Output Capacitance		---	326	---	
Crss	Reverse Transfer Capacitance		---	247	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$\text{V}_{\text{G}}=\text{V}_{\text{D}}=0\text{V}$, Force Current	---	---	64	A
I_{SM}	Pulsed Source Current ^{2,5}		---	---	130	A
V_{SD}	Diode Forward Voltage ²	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=1\text{A}$, $\text{T}_J=25^\circ\text{C}$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$\text{I}_F=10\text{A}$, $d\text{I}/dt=100\text{A}/\mu\text{s}$,	---	24	---	nS
Q_{rr}	Reverse Recovery Charge	$\text{T}_J=25^\circ\text{C}$	---	28	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $\text{V}_{\text{DD}}=25\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{L}=0.1\text{mH}$, $\text{I}_{\text{AS}}=60\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.
- 6.Package limitation current is 90A.



Typical Characteristics

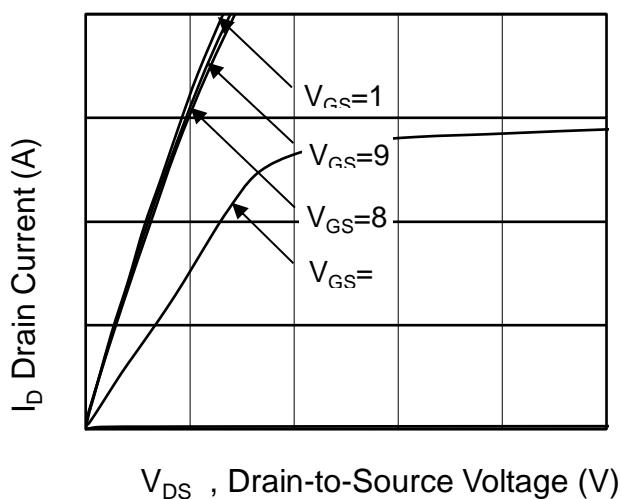


Fig.1 Typical Output Characteristics

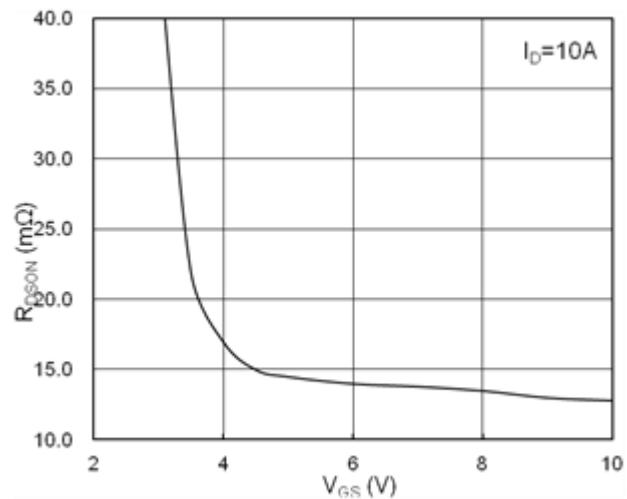


Fig.2 On-Resistance v.s Gate-Source

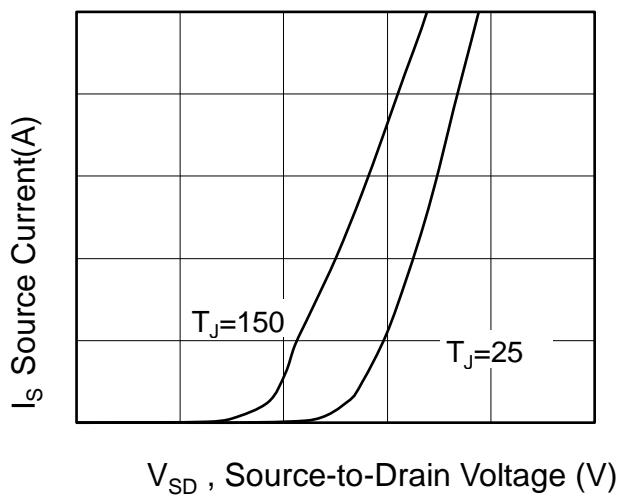


Fig.3 Forward Characteristics of Reverse

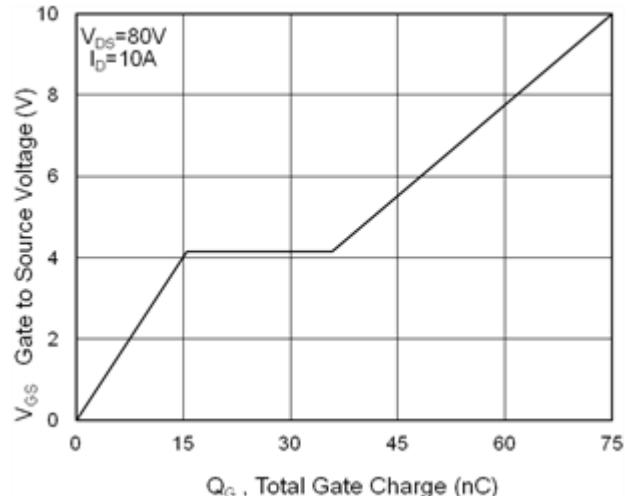


Fig.4 Gate-Charge Characteristics

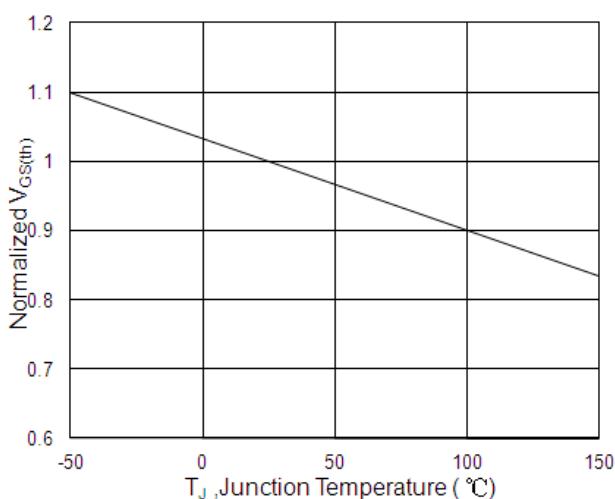


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

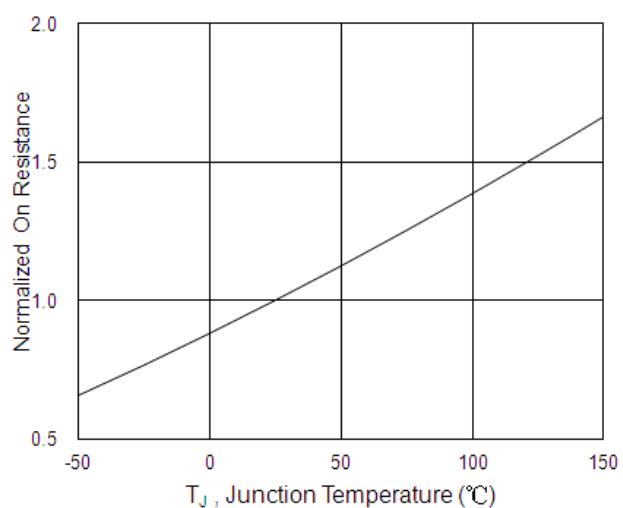
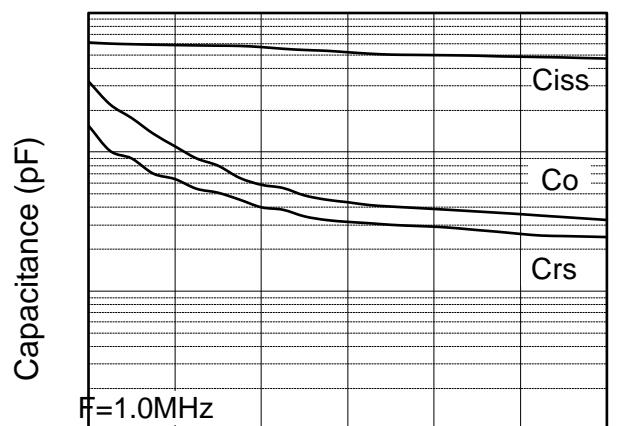
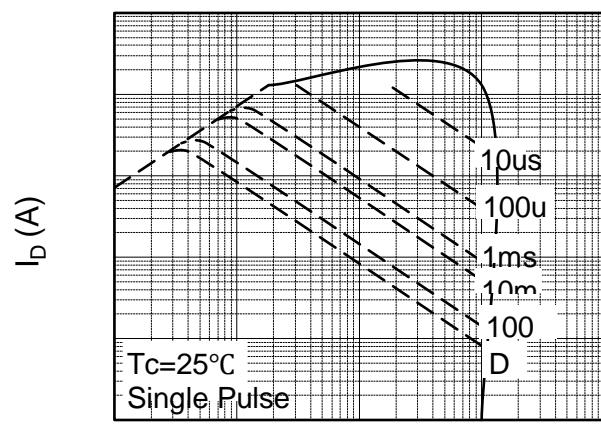


Fig.6 Normalized $R_{DS(on)}$ vs. T_J



V_{DS} , Drain to Source Voltage(V)



V_{DS} (V)

Fig.7 Capacitance

Fig.8 Safe Operating Area

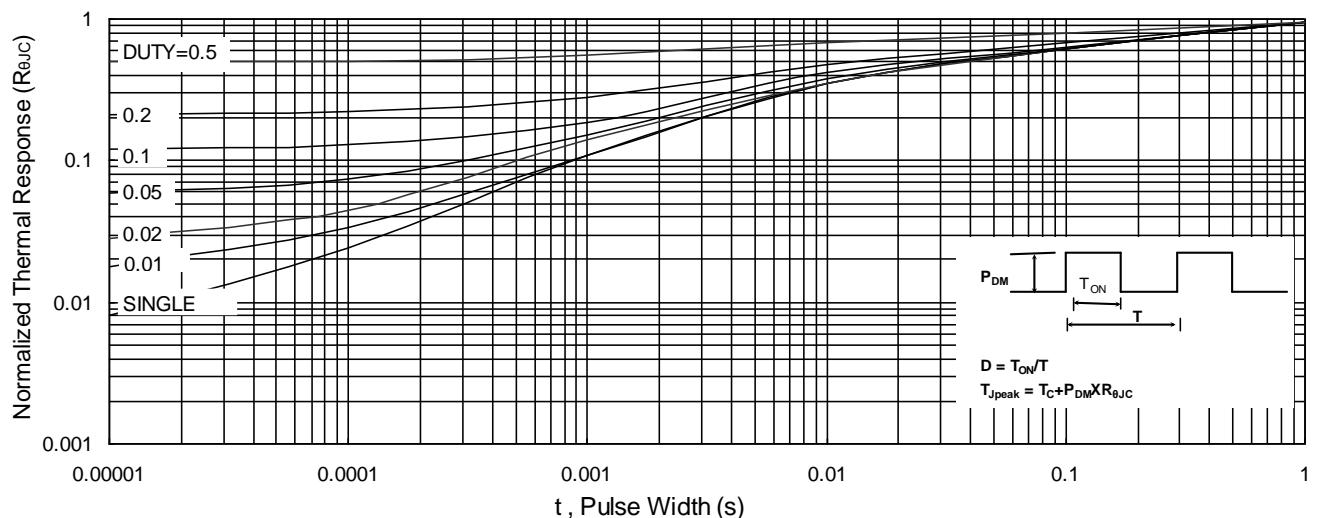


Fig.9 Normalized Maximum Transient Thermal Impedance

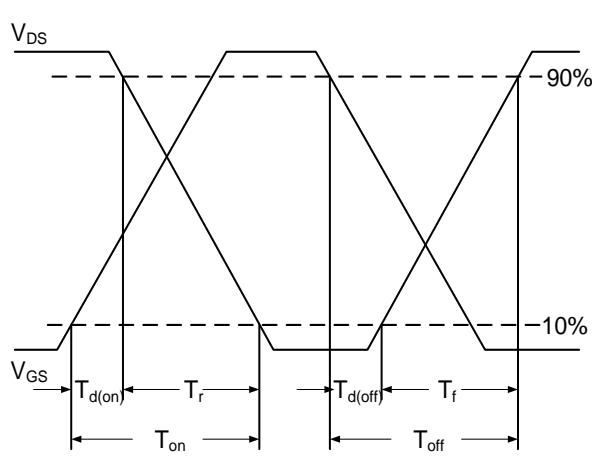


Fig.10 Switching Time Waveform

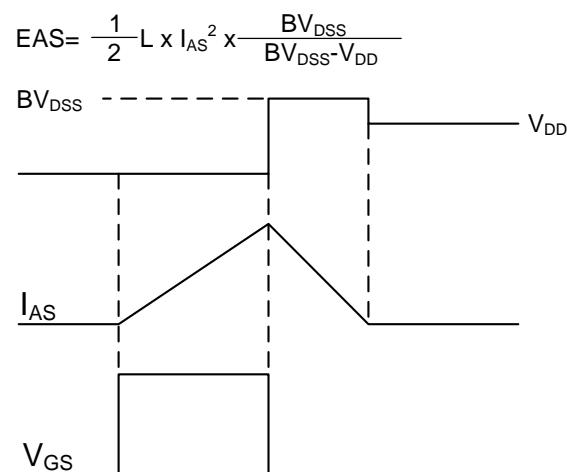


Fig.11 Unclamped Inductive Switching Waveform



Ordering Information

Part Number	Package code	Packaging
HSBA0040	PRPAK5*6	3000/Tape&Reel

